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Attorney Docket No. 9180-30

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
In re: Jong-Rong Jan et al.
Application No.: 10/780,529
Filed: February 17, 2004
For: *Methods Of Selectively Bumping Integrated Circuit Substrates And Related Structures*

Confirmation No.: 1502
Group Art Unit: 2818
Examiner: Chuong A. Luu
Date: November 10, 2005

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

**INFORMATION DISCLOSURE STATEMENT
PURSUANT TO 37 C.F.R. §1.97(c)**

Sir:

Attached is a list of documents on Form PTO-1449, together with a copy of any listed foreign patent document and/or non-patent literature. A copy of any listed U.S. patent and/or U.S. patent application publication is not provided herewith in accordance with the amendment by the U.S. Patent and Trademark Office to 37 C.F.R. § 1.98(a)(2)(ii) effective October 21, 2004.

This Information Disclosure Statement is submitted in accordance with 37 C.F.R. § 1.97(c), before final Office Action or Allowance, whichever is earlier.

In accordance with the requirements of 37 C.F.R. § 1.97(c)(2), a check for the \$180.00 fee specified in 37 C.F.R. § 1.17(p) is enclosed. This amount is believed to be correct. However, the Commissioner is authorized to charge any deficiency or credit any overpayment to Deposit Account No. 50-0220.

It is requested that these documents be considered by the Examiner and officially made of record in accordance with the provisions of 37 C.F.R. §1.56 and Section 609 of the MPEP.

Respectfully submitted,


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Sheena L. Donnelly

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INFORMATION DISCLOSURE
STATEMENT BY APPLICANT

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Sheet 1 of 7

Complete if Known

Application Number	10/780,529
Filing Date	February 17, 2004
First Named Inventor	Jong-Rong Jan
Group Art Unit	2818
Examiner Name	Chuong A. Luu
Attorney Docket Number	9180-30

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Sheet	2	of	7	Attorney Docket Number	9180-30
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Complete if Known	
Application Number	10/780,529
Filing Date	February 17, 2004
First Named Inventor	Jong-Rong Jan
Group Art Unit	2818
Examiner Name	Chuong A. Luu

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Sheet	3	of	7	Attorney Docket Number	9180-30
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Complete if Known					
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Examiner Signature		Date Considered	
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Substitute form 1449A/PTO INFORMATION DISCLOSURE STATEMENT BY APPLICANT <i>(use as many sheets as necessary)</i>				Complete if Known		
Sheet	5	of	7	Application Number	10/780,529	
				Filing Date	February 17, 2004	
				First Named Inventor	Jong-Rong Jan	
				Group Art Unit	2818	
				Examiner Name	Chuong A. Luu	
				Attorney Docket Number	9180-30	

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Examiner Initials*	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published	T
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Examiner Signature		Date Considered	
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INFORMATION DISCLOSURE
STATEMENT BY APPLICANT

(use as many sheets as necessary)

				Complete if Known	
Application Number	10/780,529				
Filing Date	February 17, 2004				
First Named Inventor	Jong-Rong Jan				
Group Art Unit	2818				
Examiner Name	Chuong A. Luu				

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